

Form PTO-159S (Rev. 09/04)  
OMB No. 0651-0027 (exp. 6/30/2005)

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### RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

**1. Name of conveying party(ies)/Execution Date(s):**  
NAOKI EJIMA (02/26/2003), TOSHIROH NISHIO (03/03/2003), AKIHISA KAWAMURA (02/26/2003), HIDEKAZU SUZUKI (03/05/2003),

Execution Date(s): in parentheses after inventor name  
Additional name(s) of conveying party(ies) attached?  Yes  No

**3. Nature of Conveyance:**  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Government Interest Assignment  
 Executive Order 9424, Confirmatory License  
 Other

**2. Name and address of receiving party(ies)**  
Name: SONY CORPORATION  
Internal Address: \_\_\_\_\_  
Street Address: 1-7-1 Konan, Minato-ku  
Tokyo  
108-0075  
JAPAN  
City: \_\_\_\_\_  
State: \_\_\_\_\_  
Country: \_\_\_\_\_ Zip: \_\_\_\_\_  
Additional name(s) & address(es) attached?  Yes  No


**4. Application or patent number(s):**  
A. Patent Application No.(s)  
11/489,175  
Additional numbers attached?  Yes  No

This document is being filed together with a new application.  
B. Patent No.(s)

**5. Name and address to whom correspondence concerning document should be mailed:**  
Name: Dennis M. Smid, Esq.  
LERNER, DAVID, LITTENBERG,  
KRUMHOLZ & MENTLIK, LLP  
Internal Address: Atty. Dkt.: SONYSH 3.3-1256 CONT  
Street Address: 600 South Avenue West  
City: Westfield  
State: NJ Zip: 07090  
Phone Number: (908) 518-6374  
Fax Number: (908) 654-0415  
Email Address: dsmid@ldlkm.com

**6. Total number of applications and patents involved:** 1  
**7. Total fee (37 CFR 1.21(h) & 3.41)** \$ 40.00  
 Authorized to be charged by credit card  
 Authorized to be charged to deposit account  
 Enclosed  
 None required (government interest not affecting title)

**8. Payment Information**  
a. Credit Card Last 4 Numbers \_\_\_\_\_  
Expiration Date \_\_\_\_\_  
b. Deposit Account Number 12-1095  
Authorized User Name Bruno Polito

**9. Signature:**  February 4, 2010  
Signature Date  
Bruno Polito - 38,580  
Name of Person Signing  
Total number of pages including cover sheet, attachments, and documents: 5

CH \$40.00 121095 11489175

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**RECORDATION FORM COVER SHEET  
(continued)**

Form PTO-1595

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**Additional Conveying Party(ies)/Execution Date(s) (1. Continued):**  
 Sho Murakoshi (03/06/2003), Tetsuya Hiroe (03/07/2003), and Hiroshige Okamoto (03/07/2003)

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**Additional Assignees (2. Continued):**

Assignee Name: Matsushita Electric Industrial Co., Limited  
 Internal Address: \_\_\_\_\_  
 Street Address: 1006, Oaza Kadoma  
Kadoma-Shi, Osaka  
571-8501  
JAPAN  
 City: \_\_\_\_\_ State: \_\_\_\_\_ Country: \_\_\_\_\_ Zip: \_\_\_\_\_

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Assignee Name: \_\_\_\_\_  
 Internal Address: \_\_\_\_\_  
 Street Address: \_\_\_\_\_  
 City: \_\_\_\_\_ State: \_\_\_\_\_ Country: \_\_\_\_\_ Zip: \_\_\_\_\_

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Assignee Name: \_\_\_\_\_  
 Internal Address: \_\_\_\_\_  
 Street Address: \_\_\_\_\_  
 City: \_\_\_\_\_ State: \_\_\_\_\_ Country: \_\_\_\_\_ Zip: \_\_\_\_\_

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**Additional Applications and/or Patents (4. Continued):**

Additional Patent Application Numbers 4A. Continued:	Additional Patent Numbers 4B. Continued:
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Additional numbers attached?  Yes  No

S02P0106US00J

Docket Number 7217/66296

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in TRANSMISSION METHOD, TRANSMISSION SYSTEM, SENDING DEVICE, AND RECEIVING DEVICE for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 6-7-35 Kitashinagawa, Shinagawa-Ku, Tokyo, Japan and Matsushita Electric Industrial Co., Limited 1006, Oaza Kadoma, Kadoma-shi, Osaka, 571-8501 Japan (hereinafter referenced as ASSIGNEES) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereof;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereof;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number 10/240,156, Filing Date 09/27/02

PATENT

REEL: 023902 FRAME: 0508

S02P0106US00J

This assignment executed on the dates indicated below.

Naoki Ejima Execution date of U.S. Patent Application  
Name of first or sole inventor

Osaka, Japan  
Residence of first or sole inventor

Naoki Ejima  
Signature of first or sole inventor

02/26/03  
Date of this assignment

Toshiroh Nishio Execution date of U.S. Patent Application  
Name of second inventor

Osaka, Japan  
Residence of second inventor

Toshiroh Nishio  
Signature of second inventor

02/03/03  
Date of this assignment

Akihisa Kawamura Execution date of U.S. Patent Application  
Name of third inventor

Osaka, Japan  
Residence of third inventor

Akihisa Kawamura  
Signature of third inventor

02/26/03  
Date of this assignment

Hidekazu Suzuki Execution date of U.S. Patent Application  
Name of fourth inventor

Osaka, Japan  
Residence of fourth inventor

Hidekazu Suzuki  
Signature of fourth inventor

03/05/03  
Date of this assignment

Sho Murakoshi  
Name of fifth inventor

Execution date of U.S. Patent Application

Tokyo, Japan  
Residence of fifth inventor

Sho Murakoshi  
Signature of fifth inventor

March 6, 2003  
Date of this assignment

Tetsuya Hiroe  
Name of sixth inventor

Execution date of U.S. Patent Application

Tokyo, Japan  
Residence of sixth inventor

Tetsuya Hiroe  
Signature of sixth inventor

March 7, 2003  
Date of this assignment

Hiroshige Okamoto  
Name of seventh inventor

Execution date of U.S. Patent Application

Tokyo, Japan  
Residence of seventh inventor

Hiroshige Okamoto  
Signature of seventh inventor

MAR 7 2003  
Date of this assignment